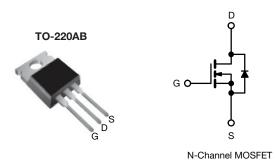


Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	500				
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	3.0			
Q _g max. (nC)	24				
Q _{gs} (nC)	3.3				
Q _{gd} (nC)	13				
Configuration	Single				

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF820PbF		
Lead (Pb)-free and halogen-free	IRF820PbF-BE3		

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-source voltage			V _{DS}	500	V		
Gate-source voltage			V_{GS}	± 20	v		
Continuous drain current	V -+ 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		2.5			
	V _{GS} at 10 V	T _C = 100 °C	I _D	1.6	Α		
Pulsed drain current ^a			I _{DM}	8.0			
Linear derating factor				0.40	W/°C		
Single pulse avalanche energy ^b			E _{AS}	210	mJ		
Repetitive avalanche current ^a			I _{AR}	2.5	А		
Repetitive avalanche energy ^a			E _{AR}	5.0	mJ		
Maximum power dissipation	T _C =	25 °C	P_{D}	50	W		
Peak diode recovery dV/dt ^c			dV/dt	3.5	V/ns		
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	- °C		
Soldering recommendations (peak temperature) d	d For 10 s		300				
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in		
				1.1	N·m		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 60 mH, R_g = 25 Ω , I_{AS} = 2.5 A (see fig. 12)
- c. $I_{SD} \le 2.5$ A, $dI/dt \le 50$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C
- d. 1.6 mm from case



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	2.5		

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static				L	L		
Drain-source breakdown voltage	V_{DS}	V _{GS} :	500	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.59	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-source leakage	I _{GSS}		V _{GS} = ± 20 V		_	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} =	V _{DS} = 500 V, V _{GS} = 0 V		-	25	μA
		V _{DS} = 400 \	V _{DS} = 400 V, V _{GS} = 0 V, T _J = 125 °C		-	250	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 1.5 A ^b	-	-	3.0	Ω
Forward transconductance	9 _{fs}	V _{DS}	= 50 V, I _D = 1.5 A	1.5	-	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 V$		-	360	-	pF
Output capacitance	C _{oss}		$V_{DS} = 25 \text{ V},$		92	-	
Reverse transfer capacitance	C _{rss}	f = 1.0 MHz, see fig. 5		-	37	-	
Total gate charge	Qg		V _{GS} = 10 V	-	-	24	nC
Gate-source charge	Q_{gs}	$V_{GS} = 10 \text{ V}$		-	-	3.3	
Gate-drain charge	Q_{gd}		occ ng. o and ro	=	-	13	
Turn-on delay time	t _{d(on)}			-	8.0	-	
Rise time	t _r	V_{DD} = 250 V, I_{D} = 2.1 A, R_{g} = 18 Ω, R_{D} = 100 Ω, see fig. 10 b		-	8.6	-	ns
Turn-off delay time	t _{d(off)}			=	33	-	
Fall time	t _f			-	16	-	
Gate input resistance	R _g	f = 1 MHz, open drain		1.8	-	12.6	Ω
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal source inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	2.5	_
Pulsed diode forward current ^a	I _{SM}			-	-	8.0	A
Body diode voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 2.5 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	1.6	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = 2.1 A, dl/dt = 100 A/μs		-	260	520	ns
Body diode reverse recovery charge	Q _{rr}			-	0.7	1.4	nC
Forward turn-on time	t _{on}	Intrincia tu	n-on is dominated by L _S and L _D)				

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width $\leq 300 \ \mu s$; duty cycle $\leq 2 \ \%$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

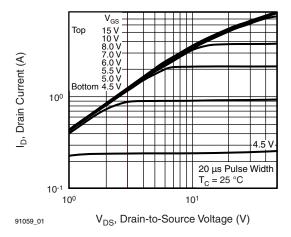


Fig. 1 - Typical Output Characteristics, $T_C = 25$ °C

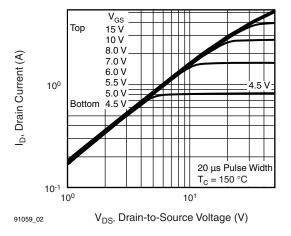


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C

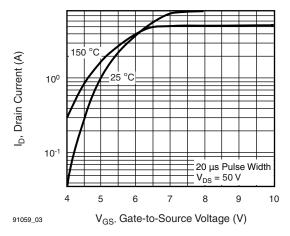


Fig. 3 - Typical Transfer Characteristics

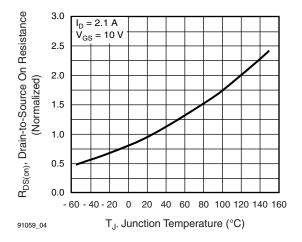


Fig. 4 - Normalized On-Resistance vs. Temperature

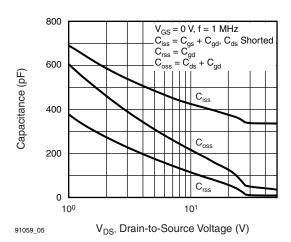


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

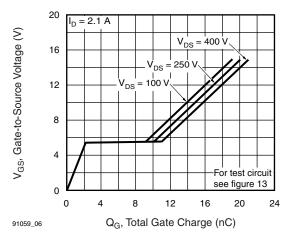


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



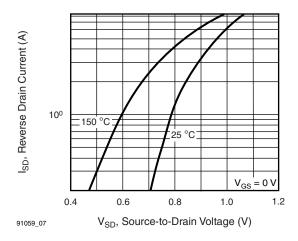


Fig. 7 - Typical Source-Drain Diode Forward Voltage

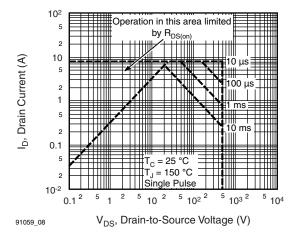


Fig. 8 - Maximum Safe Operating Area

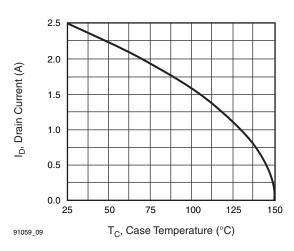


Fig. 9 - Maximum Drain Current vs. Case Temperature

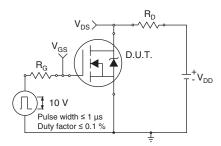


Fig. 10a - Switching Time Test Circuit

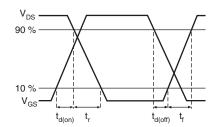


Fig. 10b - Switching Time Waveforms

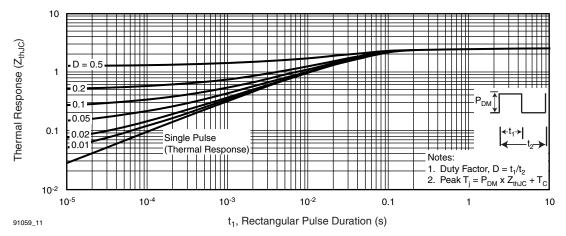


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



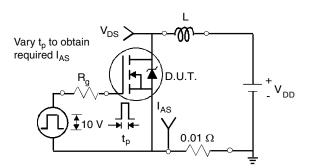


Fig. 12a - Unclamped Inductive Test Circuit

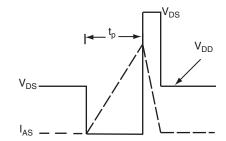


Fig. 12b - Unclamped Inductive Waveforms

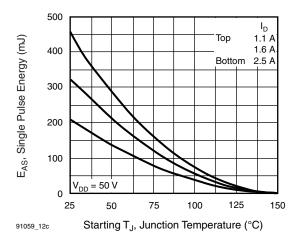


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

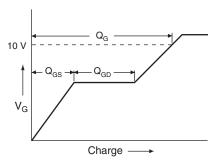


Fig. 13a - Basic Gate Charge Waveform

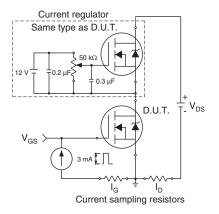
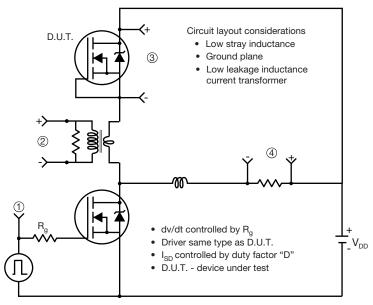


Fig. 13b - Gate Charge Test



Peak Diode Recovery dv/dt Test Circuit



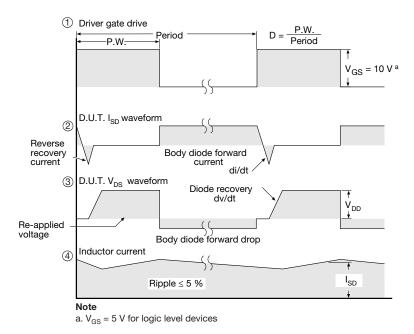


Fig. 14 - For N-Channel

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